



PTO/SB/21 (09-04)

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FORM**

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Total Number of Pages in This Submission

Application Number 09/687,048

Filing Date 10/13/2000

First Named Inventor Tae Heon Lee

Art Unit 2814

Examiner Name Nguyen, Dilinh

Attorney Docket Number AMKOR-052RCE

**ENCLOSURES (Check all that apply)**☐ Fee Transmittal Form☐ Fee Attached☒ Amendment/Reply☒ After Final☐ Affidavits/declaration(s)☐ Extension of Time Request☐ Express Abandonment Request☐ Information Disclosure Statement☐ Certified Copy of Priority Document(s)☐ Reply to Missing Parts/  
Incomplete Application☐ Reply to Missing Parts  
under 37 CFR 1.52 or 1.53☐ Drawing(s)☐ Licensing-related Papers☐ Petition☐ Petition to Convert to a  
Provisional Application  
☐ Power of Attorney, Revocation  
☐ Change of Correspondence Address☐ Terminal Disclaimer☐ Request for Refund☐ CD, Number of CD(s) \_\_\_\_\_☐ Landscape Table on CD☐ After Allowance Communication to TC☐ Appeal Communication to Board  
of Appeals and Interferences☐ Appeal Communication to TC  
(Appeal Notice, Brief, Reply Brief)☐ Proprietary Information☐ Status Letter☒ Other Enclosure(s) (please Identify  
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Remarks

**SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT**

Firm Name STETINA BRUNDA GARRED &amp; BRUCKER

Signature

Printed name Mark B. Garred

Date 5/22/06

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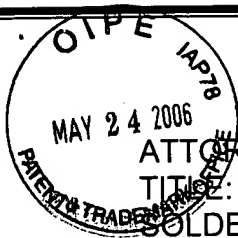
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Date 05/22/2006

This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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ATTORNEY DOCKET NO: AMKOR052RCE

TITLE: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED  
SOLDER JOINT STRENGTH

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2. Transmittal;
3. Response to Final Office Action (12 pages) and
4. Return Receipt Postcard

Application No.: 09/687,048  
Response to Office Action of March 22, 2006  
Attorney Docket: AMKOR-052A

AF  
SFW



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|             |                                    |   |                  |         |
|-------------|------------------------------------|---|------------------|---------|
| Applicants: | Lee, Tae Heon                      | ) | Confirmation No. | 1120    |
|             |                                    | ) |                  |         |
| Serial No.: | 09/687,048                         | ) | Art Unit:        | 2814    |
|             |                                    | ) |                  |         |
| Filed:      | October 13, 2000                   | ) | Examiner:        | Nguyen, |
|             |                                    | ) |                  | Dinh P. |
| For:        | Leadframe and Semiconductor        | ) |                  |         |
|             | Package With Improved Solder Joint | ) |                  |         |
|             | Strength                           | ) |                  |         |

**RESPONSE TO FINAL OFFICE ACTION UNDER 37 C.F.R. §1.116**

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Dear Sir/Madam:

Applicant hereby responds to the Final Office Action of March 22, 2006 as follows:

*Amendment to the Claims* begin on page 2 of this paper.

*Remarks* begin on page 6 of this paper.